## ABSTRACT

An n-type InP sub collector layer 2 heavily doped with silicon (Si), an InP collector layer 3, a p-type  $GaAs_{(0.51)}Sb_{(0.49)}$  base layer 4 heavily doped with carbon (C), an n-type  $In_{(1-y)}Al_{(y)}P$  emitter layer 7 doped with Si, an n-type InP cap layer 8 heavily doped with Si, and an n-type  $In_{(0.53)}Ga_{(0.47)}As$  contact layer 9 heavily doped with Si are stacked on a substrate 1.